

## **ONE STEP COPPER DAMASCENE CMP PROCESS AND SLURRY THEREFORE**

### **ABSTRACT**

A Chemical Mechanical Polish (CMP) process and slurry therefore slurry that is capable of removing NiFe, SiO<sub>2</sub>, Photoresist, Ta, alumina and Cu at substantially the same rate. The slurry is useful for obtaining a substantially planar surface of several materials while avoiding corrosion of Cu coil and NiFe structure.